

# 3A, 100V - 200V Ultra Fast Surface Mount Rectifier

#### **FEATURES**

- Planar technology
- Low power loss, high efficiency
- Ideal for automated placement
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

#### **APPLICATIONS**

- High frequency switching
- DC/DC
- Snubber

#### **MECHANICAL DATA**

- Case: DO-214AB (SMC)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.200g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I <sub>F</sub>	3	Α	
$V_{RRM}$	100 - 200	V	
I <sub>FSM</sub>	85	Α	
T <sub>J MAX</sub>	175	°C	
Package	DO-214AB (SMC)		
Configuration	Single die		









**DO-214AB (SMC)** 



PARAMETER		SYMBOL	PU3BC	PU3DC	UNIT
Marking code on the device			PU3BC	PU3DC	
Repetitive peak reverse voltage		$V_{RRM}$	100	200	V
Reverse voltage, total rms value		V <sub>R(RMS)</sub>	70	140	V
Forward current		I <sub>F</sub>	3		Α
Surge peak forward current single half	t = 8.3ms		85		A
sine-wave superimposed on rated load	t = 1.0ms	- I <sub>FSM</sub>	180		
Junction temperature		TJ	-55 to +175		°C
Storage temperature		T <sub>STG</sub>	-55 to +175		°C



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THERMAL PERFORMANCE			
PARAMETER	SYMBOL	TYP	UNIT
Junction-to-lead thermal resistance	$R_{\Theta JL}$	14	°C/W
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	58	°C/W
Junction-to-case thermal resistance	R <sub>eJC</sub>	16	°C/W

**Thermal Performance Note:** Units mounted on PCB (16mm x 16mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
	I <sub>F</sub> = 1.5A, T <sub>J</sub> = 25°C		0.81	-	V
Forward voltage <sup>(1)</sup>	I <sub>F</sub> = 3.0A, T <sub>J</sub> = 25°C	\/	0.86	0.93	V
Forward voilage	I <sub>F</sub> = 1.5A, T <sub>J</sub> = 125°C	$V_{F}$	0.66	-	V
	I <sub>F</sub> = 3.0A, T <sub>J</sub> = 125°C		0.73	-	V
Reverse current @ rated V <sub>R</sub> (2)	T <sub>J</sub> = 25°C	1	-	2	μA
	T <sub>J</sub> = 125°C	l <sub>R</sub>	-	10	μA
Junction capacitance	1MHz, $V_R = 4.0V$	CJ	47	-	pF
Payaraa raaayary tima	$I_F = 0.5A$ , $I_R = 1.0A$ , $I_{rr} = 0.25A$	4	-	25	ns
Reverse recovery time	$I_F = 1.0A$ , di/dt = 50A/ $\mu$ s, $V_R = 30V$	t <sub>rr</sub>	31	-	
Reverse recovery current		I <sub>RM</sub>	4.9	-	Α
Reverse recovery charge	$I_F = 3.0A$ , di/dt = 200A/ $\mu$ s, $V_R = 100V$	Q <sub>rr</sub>	51	-	nC
Reverse recovery time		t <sub>rr</sub>	23	-	ns

## Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION		
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING
PU3xC	DO-214AB (SMC)	3,000/ Tape & Reel

### Notes:

1. "x" defines voltage from 100V(PU3BC) to 200V(PU3DC)



### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

**Fig.1 Forward Current Derating Curve** 

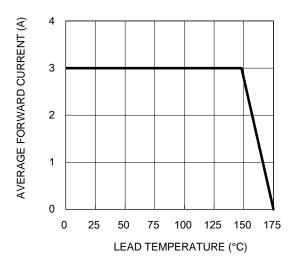


Fig.3 Typical Reverse Characteristics

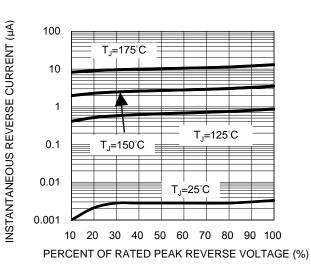


Fig.2 Typical Junction Capacitance

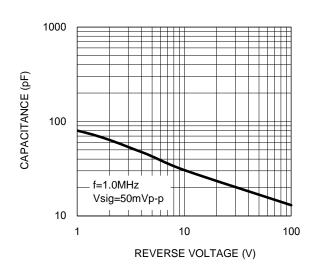


Fig.4 Typical Forward Characteristics

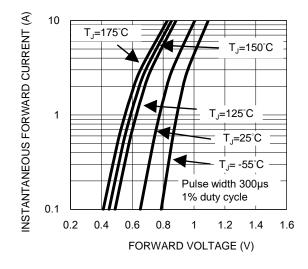
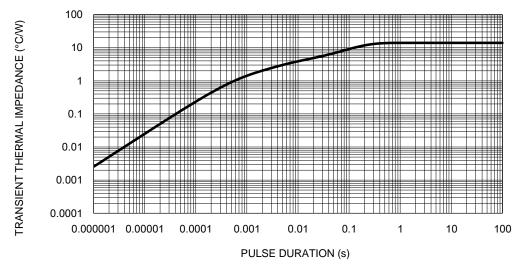


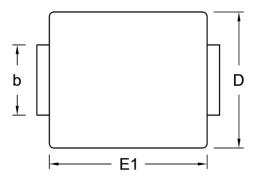
Fig.5 Typical Transient Thermal Impedance

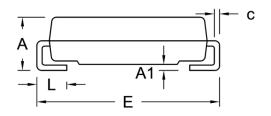




## **PACKAGE OUTLINE DIMENSIONS**

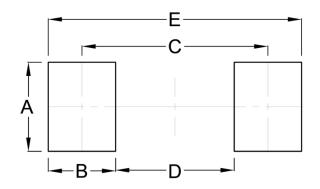
DO-214AB (SMC)





DIM.	Unit (mm)		Unit	(inch)	
Dilvi.	Min.	Max.	Min.	Max.	
Α	2.00	2.62	0.079	0.103	
A1	0.10	0.20	0.004	0.008	
b	2.90	3.20	0.114	0.126	
С	0.15	0.31	0.006	0.012	
D	5.59	6.22	0.220	0.245	
E	7.75	8.13	0.305	0.320	
E1	6.60	7.11	0.260	0.280	
L	1.00	1.60	0.039	0.063	

## **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
Α	3.30	0.130
В	2.50	0.098
С	6.90	0.272
D	4.40	0.173
E	9.40	0.370

## **MARKING DIAGRAM**



P/N = Marking Code G = Green Compound

ΥW = Date Code F = Factory Code



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